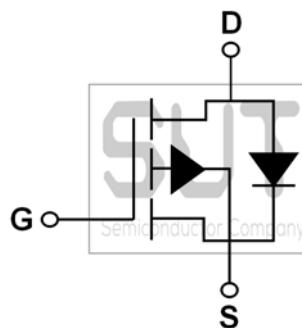
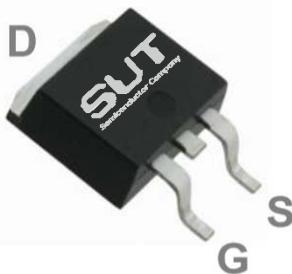


P-Channel 100-V_(D-S) MOSFET

PRODUCT SUMMARY		
B _{VDS} (V)	R _{DS(on)} (mΩ)(MAX)	I _D (A)
-100	45@V _{GS} =-10V	-30

TO252 Pin Configuration



ABSOLUTE MAXIMUM RATINGS(T_C=25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	-100	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous (T _C =25°C)	I _D	-30	A
Drain Current-Continuous (T _C =100°C)		-19	A
Drain Current-Pulsed ¹	I _{DM}	-120	A
Single Pulse Avalanche Energy ²	EAS	180	mJ
Single Pulse Avalanche Current ²	IAS	-60	A
Power Dissipation (T _C =25°C)	P _D	102	W
Power Dissipation-Derate above 25°C		0.82	W/°C
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

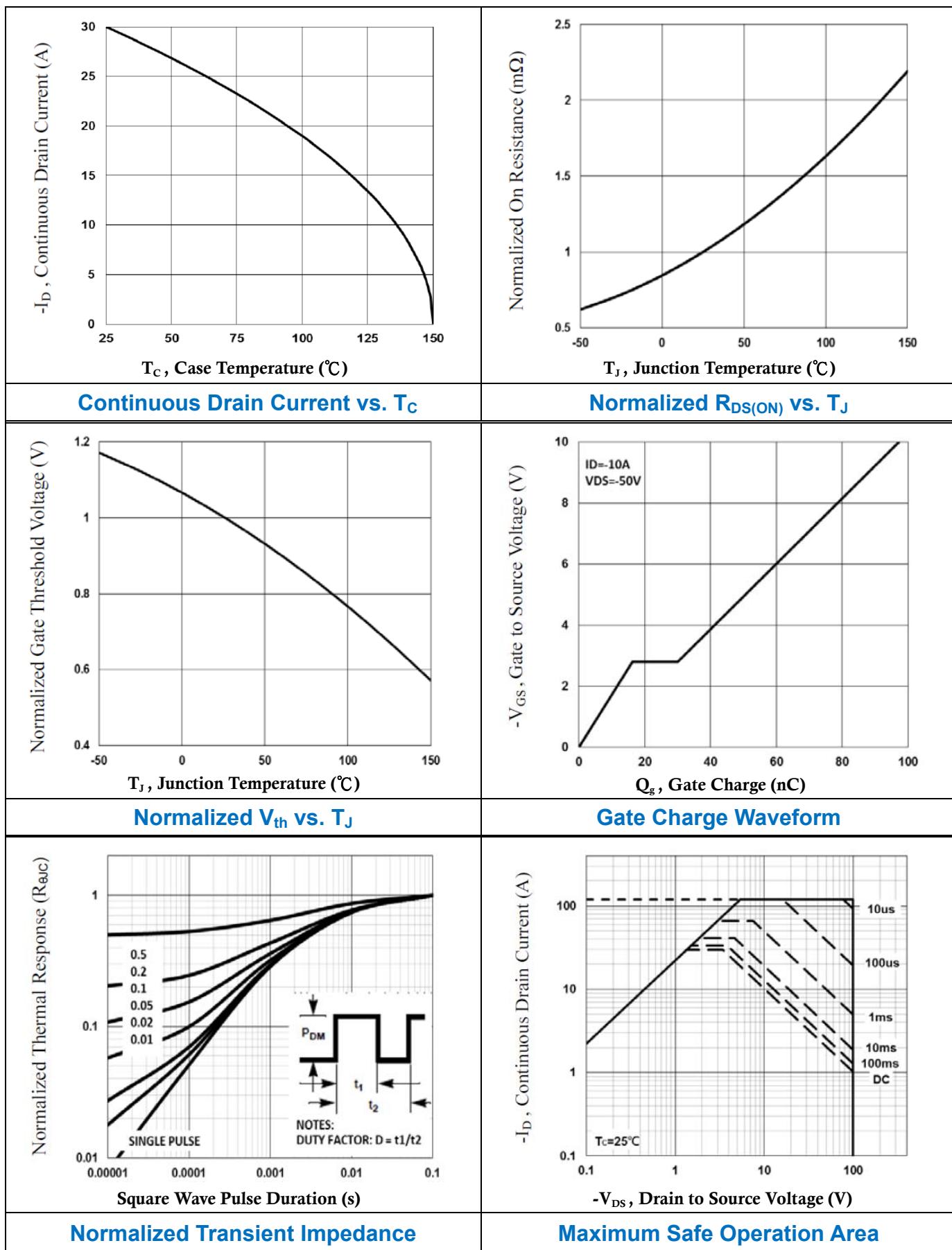
THERMAL CHARACTERISTICS

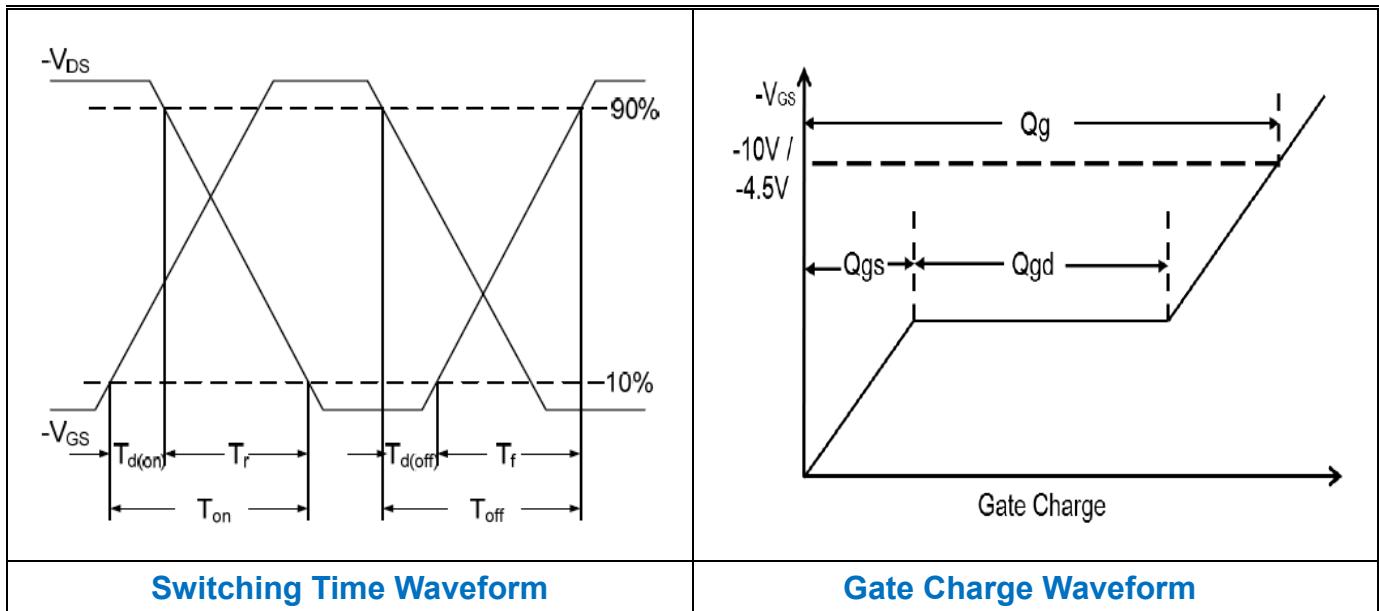
Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to ambient	R _{θJA}	---	62	°C/W
Thermal Resistance Junction to Case	R _{θJC}	---	1.22	°C/W

ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-100	---	---	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-100\text{V}, T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-80\text{V}, T_J=85^\circ\text{C}$	---	---	-10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
On Characteristics						
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-15\text{A}$	---	36	45	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-10\text{A}$	---	40	55	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-1.2	---	-2.5	V
Forward Transconductance	g_{fs}	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-5\text{A}$	---	22	---	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3, 4}	Q_g	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-50\text{V}, I_{\text{D}}=-10\text{A}$	---	98	150	nC
Gate-Source Charge ^{3, 4}	Q_{gs}		---	16.2	30	
Gate-Drain Charge ^{3, 4}	Q_{gd}		---	13.8	26	
Turn-On Delay Time ^{3, 4}	$T_{\text{d(on)}}$	$V_{\text{GS}}=-10\text{V}, V_{\text{DD}}=-50\text{V}, R_G=25\Omega, I_{\text{D}}=-5\text{A}$	---	58	105	ns
Rise Time ^{3, 4}	T_r		---	24	50	
Turn-Off Delay Time ^{3, 4}	$T_{\text{d(off)}}$		---	215	450	
Fall Time ^{3, 4}	T_f		---	94	180	
Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-25\text{V}, F=1\text{MHz}$	---	6315	9000	pF
Output Capacitance	C_{oss}		---	220	330	
Reverse Transfer Capacitance	C_{rss}		---	50	100	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V}$, Force Current	---	---	-30	A
Pulsed Source Current	I_{SM}		---	---	-60	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_s=-1\text{A}, T_J=25^\circ\text{C}$	---	---	-1.0	V

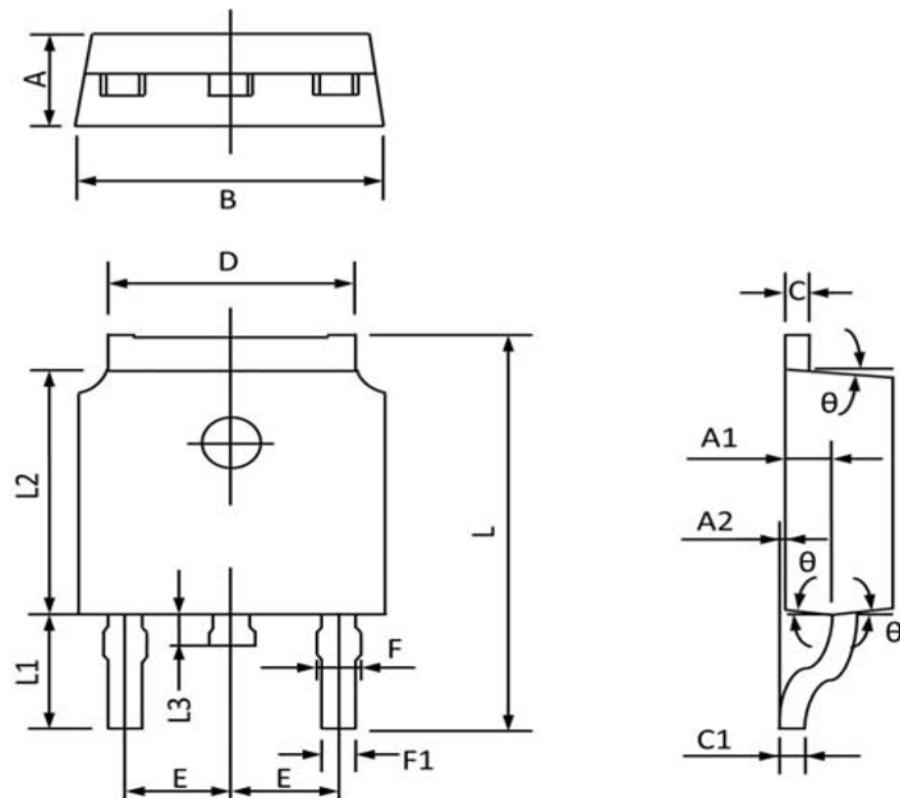
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{GS}}=-10\text{V}, V_{\text{DD}}=-50\text{V}, L=0.1\text{mH}, I_{\text{AS}}=-60\text{A}, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.





TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°